

Application/Control Number: 10/607,628

Page 2

Art Unit: 0

CLAIM PTO

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11/04/04

Art Unit: 0

1. A method of determining terminals of a semiconductor die to contact during test, said method comprising:
 - selecting a first subset of said terminals not to contact during testing of said die;
 - covering with an electrically insulative material tip(s) of a first subset of probes corresponding to said first subset of terminals, wherein said first subset of probes composes a plurality of probes corresponding to ones of said terminals;
 - bringing said plurality of probes into contact with said ones of said terminals of said die; and
 - verifying testing of said die.
2. The method of claim 1, wherein said first subset of terminals comprises one terminal.
3. The method of claim 1, wherein said first subset of terminals comprises at least two terminals.
4. The method of claim 1, wherein, if said testing of said die does not verify, said method further comprises:
 - selecting a second subset of said terminals not to contact during testing of said die;
 - removing said insulative material from said tip(s) of said first subset of probes;
 - covering with an insulative material tip(s) of a second subset of probes corresponding to said second subset of terminals;
 - bringing said plurality of probes into contact with said ones of said terminals of said die; and
 - verifying testing of said die.
5. The method of claim 4, wherein said step of removing said insulative material comprises removing said insulative material by dissolving, laser ablating, peeling, air blasting, water blasting, burning, or subliming said insulative material.
6. The method of claim 1, wherein said plurality of probes are disposed on a probe card.

Art Unit: 0

7. The method of claim 1, wherein said die composes an unsingulated semiconductor wafer.
8. The method of claim 1, wherein said insulative material comprises a material selected from one of an epoxy, a nylon, a starch, a vinyl, a styrene, a polyethylene, a polypropylene, a thermoplastic, or a rubber.
9. The method of claim 1, wherein said plurality of probes are cantilevered beam probes.

CLAIMS 10-18 CANCELED